DS07-12521-3E

8-bit Proprietary Microcontroller

CMOS

F²MC-8L MB89910 Series

MB89913/915/P915/PV910

DESCRIPTION

The MB89910 series has been developed as a general-purpose version of the F²MC*-8L family consisting of proprietary 8-bit, single-chip microcontrollers.

In addition to a compact instruction set, the microcontrollers contain a variety of peripheral functions such as dual-clock control system, five operating speed control stages, timers, a serial interface, an A/D converter, a buzzer output, a low-voltage detection reset, high-voltage driver, a watch prescaler, and external interrupts. The MB89910 series is applicable to a wide range of applications from consumer products to industrial equipments.

*: F²MC stands for FUJITSU Flexible Microcontroller.

■ FEATURES

- Minimum execution time: 0.50 μs/8.0 MHz oscillation
- Interrupt processing time: 4.50 μs/8.0 MHz oscillation
- F²MC-8L family CPU core

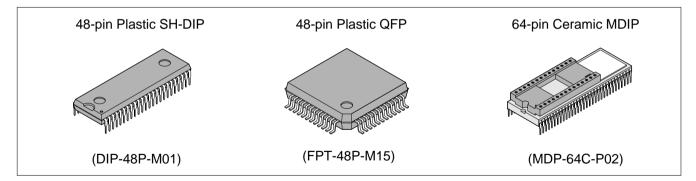
Instruction set optimized for controllers

Multiplication and division instructions 16-bit arithmetic operations Test and branch instructions Bit manipulation instructions, etc.

Dual-clock control system

(Continued)

PACKAGE



- High-voltage ports (built-in a pull-down resistor capable)
 8 ports for large current
 10 ports for small current
- 8-bit PWM timer: 1 channel
- 16-bit timer/counter: 1 channel
- 21-bit timebase timer
- 8-bit serial I/O: 1 channel
- 8-bit A/D converter: 8 channels
- External interrupt
 Edge detection function
 Two channels, including one of
- Two channels, including one of which voltage can be applied from –0.3 to +7.0 V • Low-voltage detection reset (excluding the MB89PV910)
- Low-power consumption modes (subclock mode, watch mode, sleep mode, and stop mode)
- Reset output and power-on reset function
- Watch prescaler

■ PRODUCT LINEUP

Part number Parameter	MB89913	MB89915	MB89P915	MB89PV910		
Classification		ction product M product)	One-time PROM product	Piggyback/ evaluation product (for evaluation and development)		
ROM size	8 K × 8 bits (internal mask ROM)	16 K × 8 bits (internal mask ROM)	16 K × 8 bits (internal PROM, programmable with general-purpose EPROM programmer)	32K × 8 bits (Piggyback) (External ROM)		
RAM size	256×8 bits	512 ×	8 bits	1 K × 8 bits		
CPU functions	Number of instructions:136Instruction bit length:8 bitsInstruction length:1 to 3 bytesData bit length:1, 8, 16 bitsMinimum execution time:0.50 μs/8.0 MHz to 8.00 μs/8.0 MHz, or61 μs/32.768 kHzInterrupt processing time:4.5 μs/8.0 MHz to 72.0 μs/8.0 MHz, or549.3 μs/32.768 kHzNote: The above times depend on the gear function.					
Ports	High-voltage output ports (P-ch open-drain): 8 (P10 to P17 for large current) 10 (P20 to P27 and P50 to P51 for small current)I/O ports (CMOS):13 (P00 to P07, P34 to P37, and P40)I/O ports (N-ch open-drain):6 (P30 to P33, P41, P42)Input ports (CMOS):2 (P60 and P61 also serve as a subclock pin)Total:39					
Timebase timer (Timer 1)	Capable of generating four different intervals at 8.0-MHz oscillation: 0.26, 0.51, 1.02, and 524.0 ms					
8-bit PWM timer (Timer 2)	 8-bit timer operation (square wave output capable. Operation clock: 1, 2, 8, or 16 instruction cycles) 8-bit resolution PWM operation (Conversion cycle: 128 μs to 2.0 ms at 8.0 MHz) 					
16-bit timer/counter (Timer 3)	16-bit timer operation (operating clock: 1 instruction cycle) 16-bit event counter operation (Rising/falling/both edges selectable)					
8-bit serial I/O	8 bits LSB first/MSB first selectable Transfer clock (external, 4/8/16 instruction cycles)					
8-bit A/D converter	8-bit resolution × 8 channels A/D conversion mode (conversion time of 22.0 μs/8.0 MHz) Sense mode (conversion time of 6.0 μs/8.0 MHz) Continuous activation enabled by external clock or internal clock Reference voltage input (AVR) is provided.					

(Continued)

Part number Parameter	MB89913	MB89915	MB89P915	MB89PPV910		
External interrupt	2 independent channels (edge selection, interrupt vector, factor flag) Rising/ falling/both edges selectable Built-in analog noise canceller Used also for wake-up stop/sleep modes. (Edge detection is also permitted in stop mode.)					
Low-voltage detection reset	Continuous operation (de 3. Intermittent operation (Ac du	Not available				
Low-power consumption (Standby mode)	Sleep mode, stop mode, and watch mode					
Process	CMOS					
Operating voltage*						
EPROM for use				MBM27C256A-20CZ		

* : Varies with conditions such as the operating frequency. (See section "■ Electrical Characteristics.") In the case of the MB89PV910, the voltage varies with the ICE or the EPROM to be connected.

■ PACKAGE AND CORRESPONDING PRODUCTS

Package	MB89913 MB89915 MB89P915	MB89PV910
DIP-48P-M01	0	×
FPT-48P-M15	⊖*1	×
MDP-64C-P02	×	○*2

 \bigcirc : Available \times : Not available

*1: Under examination for development

*2: Available by conversion from MDIP-64 to SH-DIP-48 64SD-48SD-8L2: For conversion (MDP-64C-P02) \rightarrow DIP-48P-M01 Inquiry: Sun Hayato Co., Ltd.: TEL: (81)-3-3986-0403 FAX: (81)-3-5396-9106

Note: For more information about each package, see section "
Package Dimensions."

■ DIFFERENCES AMONG PRODUCTS

1. Memory Size

Before evaluating using the piggyback product, verify its differences from the product that will actually be used. Take particular care on the following points:

• The stack area, etc., is set at the upper limit of the RAM.

2. Current Consumption

- In the case of the MB89PV910, add the current consumed by the EPROM which is connected to the top socket.
- When operated at low speed, the product with an OTPROM (one-time PROM) or an EPROM will consume more current than the product with a mask ROM.

However, the current consumption in sleep/stop modes is the same. (For more information, see sections "■ Electrical Characteristics" and "■ Example Characteristics.")

3. Mask Options

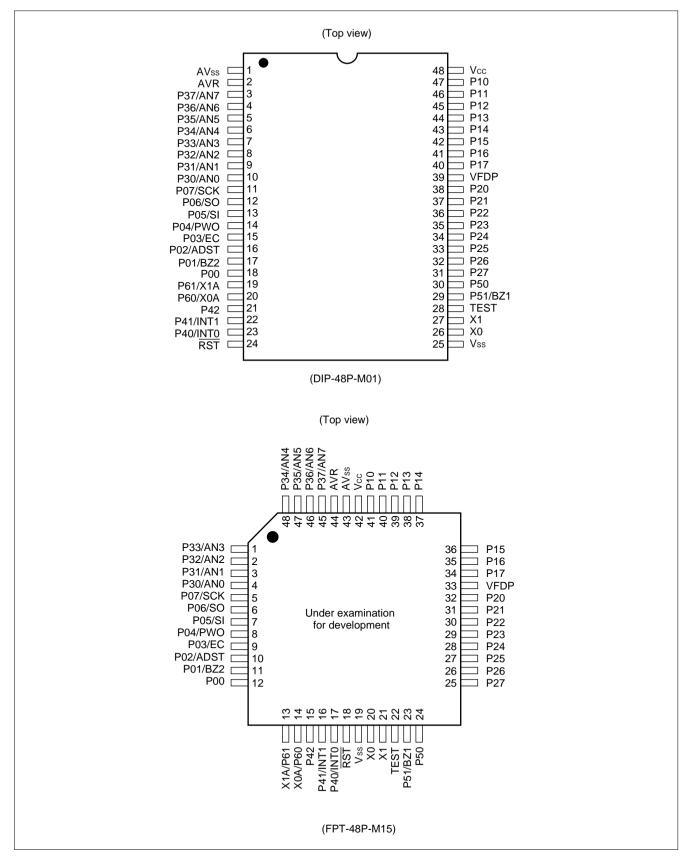
Functions that can be selected as options and how to designate these options vary by the product.

Before using options check section "■ Mask Options."

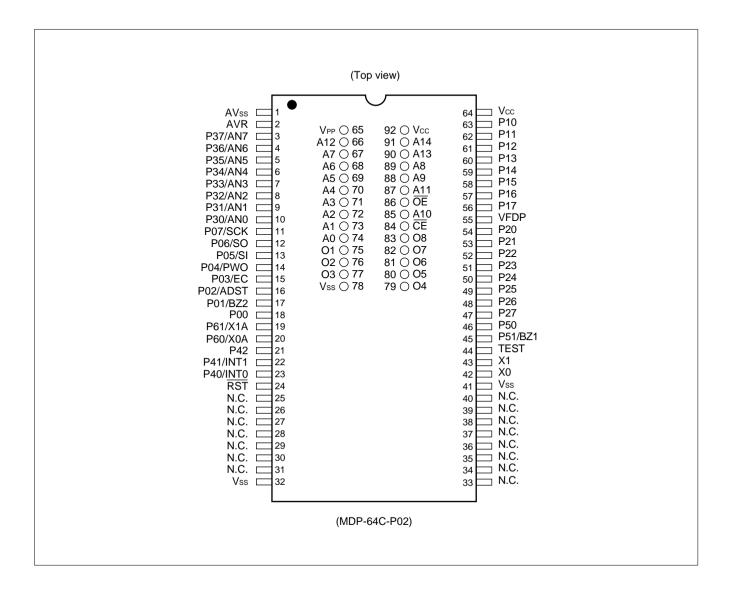
Take particular care on the following points:

- A pull-down resistor for P10 to P17, P20 to P27, and for P50 to P51 cannot be set for the MB89P915 and MB89PV910. The MB89915 and MB89913 allow a pull-down resistor to be set for individual pins. Such pins on the MB89P915 and MB89PV910 are fixed to have no pull-down resistor.
- The low-voltage detection reset cannot be used on the MB89PV910. The voltage to be detected by the lowvoltage detection reset is set by using a register for the MB89P915 and by using a mask option for the MB89915 and MB89913. If the detection voltage has been set to a lower value than the operating voltage, however, use the gear function to operate the device with the faster clock at a lower speed, or operate the device with the slower clock. Note that the results of operation are unpredictable if the device is attempted to operate at a lower voltage than the operating voltage with the faster clock put in top gear.

PIN ASSIGNMENT



To Top / Lineup / Index MB89910 Series



■ PIN DESCRIPTION

Pin no.			Circuit	- .:	
SH-DIP*1	QFP*2	MDIP*3	Pin name	type	Function
26	20	42	X0	A	Main clock crystal oscillator pins
27	21	43	X1		
20	14	20	X0A/P60	I	These pins can select either general-purpose CMOS inputs or subclock oscillator pins by the mask options. When these pins are used as a general-purpose input
19	13	19	X1A/P61		pin, the pin is a hysteresis input with a built-in noise canceller.
24	18	24	RST	С	Reset I/O pin This pin is an N-ch open-drain output type with pull-up resistor and a hysteresis input type. "L" is output from this pin by an internal source. The internal circuit is initialized by the input of "L". This pin is with a noise canceller.
18	12	18	P00	D	General-purpose CMOS I/O port This port input is a hysteresis input, with a built-in noise canceller.
17	11	17	P01/BZ2	D	General-purpose CMOS I/O port This port input is a hysteresis input, with a built-in noise canceller. Also serves as a buzzer output.
16	10	16	P02/ADST	D	General-purpose CMOS I/O port This port input is a hysteresis input, with a built-in noise canceller. Also serves as the external activation pin for the A/D converter.
15	9	15	P03/EC	D	General-purpose CMOS I/O port This port input is a hysteresis input, with a built-in noise canceller. Also serves as the external clock input for the 16-bit timer/counter.
14	8	14	P04/PWO	D	General-purpose CMOS I/O port This port input is a hysteresis input, with a built-in noise canceller. Also serves as the PWM output for the 8-bit PWM timer.
13, 12	7, 6	13, 12	P05/SI, P06/SO	D	General-purpose CMOS I/O ports These port inputs are a hysteresis input, with a built-in noise canceller. Also serve as serial data outputs for the 8-bit serial interface.
11	5	11	P07/SCK	D	General-purpose CMOS I/O port This port input is a hysteresis input, with a built-in noise canceller. Also serves as the serial transfer clock output for the 8-bit serial interface.
47 to 40	41 to 34	63 to 56	P10 to P17	G	P-ch high-voltage open-drain output ports for large current

*1: DIP-48P-M01

*2: FPT-48P-M15

*3: MDP-64C-P02

(Continued)

	Pin no.		Pin name	Circuit	Function
SH-DIP*1	QFP*2	MDIP*3	type		Function
38 to 31	32 to 25	54 to 47	P20 to P27	G	P-ch high-voltage open-drain output ports for small current
10 to 7	4 to 1	10 to 7	P30/AN0 to P33/AN3	H	General-purpose N-ch open-drain I/O ports These port inputs are a hysteresis input, each with a built-in noise canceller. Although the pins are also serve as an analog inputs, an analog input does not pass through their noise cancellers.
6 to 3	48 to 45	6 to 3	P34/AN4 to P37/AN7	F	General-purpose CMOS I/O ports These port inputs are a hysteresis input, each with a built-in noise canceller. Although the pins are also serve as an analog inputs, an analog input does not pass through their noise cancellers.
23	17	23	P40/INT0	D	General-purpose CMOS I/O port This port input is a hysteresis input, with a built-in noise canceller. Also serves as an external interrupt. External interrupt input passes through the noise canceller.
22	16	22	P41/INT1	E	General-purpose N-ch open-drain I/O port This port input is a hysteresis input, with a built-in noise canceller. Also serves as an external interrupt. External interrupt input passes through the noise canceller.
21	15	21	P42	E	General-purpose N-ch open-drain I/O port This port input is a hysteresis input, with a built-in noise canceller.
30	24	46	P50	G	P-ch high-voltage open-drain output ports for small current
29	23	45	P51/BZ1	G	P-ch high-voltage open-drain output port for small current Also serves as a buzzer output.
28	22	44	TEST	В	Operating mode selection pin Usually, connect to Vss directly. On the product with an EPROM, the pin is the VPP pin.
39	33	55	VFDP		Voltage supply pin connected to a pull-down resistor for ports 1, 2, and 5 In products without a pull-down resistor, in the MB89P915, and in the MB89PV910, this pin should be left open.

*1: DIP-48P-M01

*2: FPT-48P-M15

*3: MDP-64C-P02

(Continued)

	Pin no.		Pin name	Circuit	Function
SH-DIP*1	QFP*2	MDIP*3		type	Function
48	42	64	Vcc	_	Power supply pin
25	19	32, 41	Vss		Power supply (GND) pin
1	43	1	AVss		A/D converter power supply pin Use this pin at the same voltage as Vss.
2	44	2	AVR	_	A/D converter reference voltage input pin

*1: DIP-48P-M01

*2: FPT-48P-M15

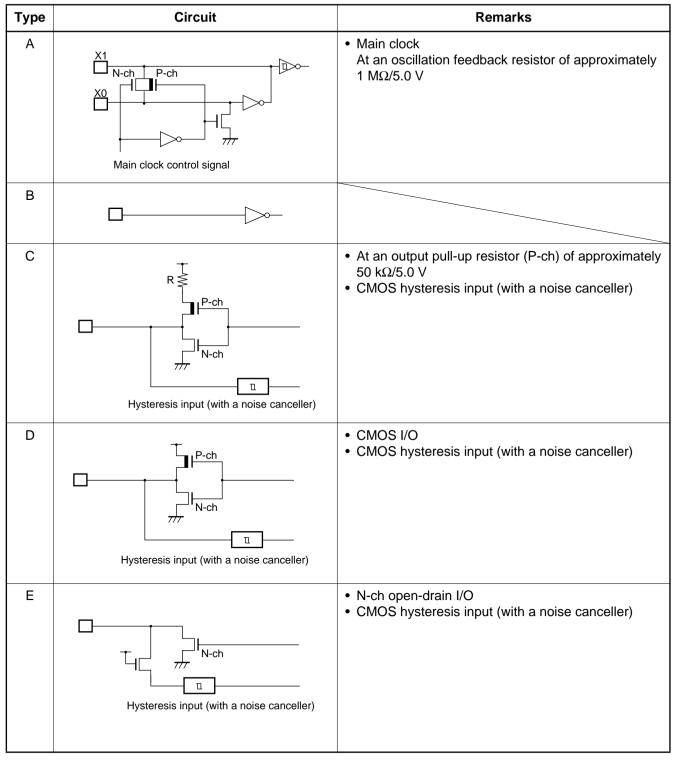
*3: MDP-64C-P02

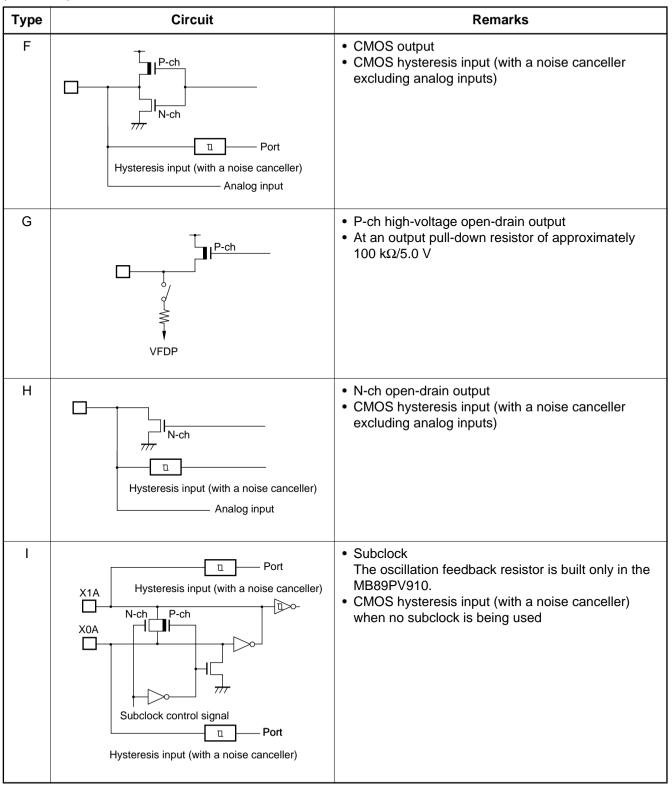
• External EPROM pins (MDIP only)

Pin no.	Dia a sur s	1/0	Function
MDIP*	Pin name	I/O	Function
65	Vpp	0	"H" level output pin
66 67 68 69 70 71 72 73 74	A12 A7 A6 A5 A4 A3 A2 A1 A0	0	Address output pins
75 76 77	01 02 03	I	Data input pins
78	Vss	0	Power supply (GND) pin
79 80 81 82 83	O4 O5 O6 O7 O8	I	Data input pins
84	CE	0	ROM chip enable pin Outputs "H" during standby.
85	A10	0	Address output pin
86	ŌĒ	0	ROM output enable pin Outputs "L" at all times.
87 88 89	A11 A9 A8	0	Address output pin
90	A13	0	
91	A14	0	
92	Vcc	0	EPROM power supply pin

* : MDP-64C-P02

■ I/O CIRCUIT TYPE





■ HANDLING DEVICES

1. Preventing Latchup

Latchup may occur on CMOS ICs if voltage higher than Vcc or lower than Vss is applied to input and output pins other than medium- and high-voltage pins or if higher than the voltage which shows on "1. Absolute Maximum Ratings" in section "
Electrical Characteristics" is applied between Vcc and Vss.

When latchup occurs, power supply current increases rapidly and might thermally damage elements. When using, take great care not to exceed the absolute maximum ratings.

Also, take care to prevent the analog power supply (AVcc and AVR) and analog input from exceeding the digital power supply (Vcc) when the analog system power supply is turned on and off.

2. Treatment of Unused Input Pins

Leaving unused input pins open could cause malfunctions. They should be connected to a pull-up or pull-down resistor.

3. Treatment of Power Supply Pins on Microcontrollers with A/D and D/A Converters

Connect to be AVcc = DAVC = Vcc and AVss = AVR = Vss even if the A/D and D/A converters are not in use.

4. Treatment of N.C. Pins

Be sure to leave (internally connected) N.C. pins open.

5. Power Supply Voltage Fluctuations

Although V_{CC} power supply voltage is assured to operate within the rated range, a rapid fluctuation of the voltage could cause malfunctions, even if it occurs within the rated range. Stabilizing voltage supplied to the IC is therefore important. As stabilization guidelines, it is recommended to control power so that V_{CC} ripple fluctuations (P-P value) will be less than 10% of the standard V_{CC} value at the commercial frequency (50 to 60 Hz) and the transient fluctuation rate will be less than 0.1 V/ms at the time of a momentary fluctuation such as when power is switched.

6. Precautions when Using an External Clock

When an external clock is used, oscillation stabilization time is required even for power-on reset (optional) and wake-up from stop mode.

■ PROGRAMMING TO EPROM ON THE MB89P915

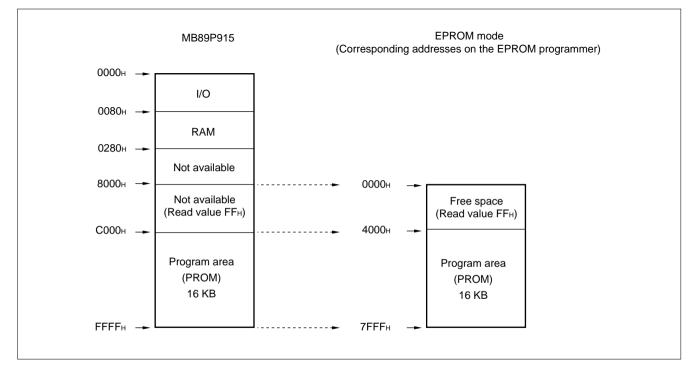
The MB89P915 is an OTPROM version of the MP89910 series.

1. Features

• 16-Kbyte PROM on chip

2. Memory Space

Memory space in each mode such as 16-Kbyte PROM mode is diagrammed below.



3. Programming to the EPROM

Since the MB89P915 requires a special method for programming to its PROM, the types of general-purpose EPROM programmers applicable to the MB89P915 are limited. Programming to the PROM on the MB89P915 requires an EPROM programmer applicable to the MB89P915 and a dedicated adapter.

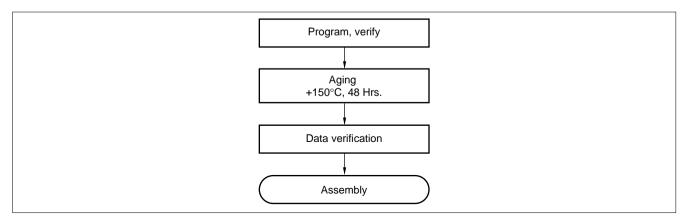
When the operating ROM area for a single chip is 16 Kbytes (C000_H to FFFF_H) the PROM can be programmed as follows:

• Programming procedure

- (1) Set the EPROM programmer to the MB89P195.
- (2) Load program data into the EPROM programmer at 4000^H to 7FFF^H. (note that addresses 0C000^H to 0FFF^H in the operation mode correspond to 4000^H to 7FFF^H in EPROM mode.)
- (3) Program with the EPROM programmer.

4. Recommended Screening Conditions

High-temperature aging is recommended as the pre-assembly screening procedure for a product with a blanked OTPROM microcomputer program.



5. Programming Yield

All bits cannot be programmed at Fujitsu shipping test to a blanked OTPROM microcomputer, due to its nature. For this reason, a programming yield of 100% cannot be assured at all times.

6. EPROM Programmer Socket Adapter and Recommended Programmer Manufacturer

				led programmer n d programmer na	
Part no.	Package	Compatible socket adapter Sun Hayato Co., Ltd.	Data I/O Co., Ltd.		d.
			UNISITE (ver.5.0 or later)	3900 (ver.2.8 or later)	2900 (ver.3.8 or later)
MB89P915P-SH	SH-DIP-48	ROM-48QF2-28DP-8L		Recommended	

Inquiry: Sun Hayato Co., Ltd.: TEL: (81)-3-3986-0403 FAX: (81)-3-5396-9106 Data I/O Co., Ltd.: TEL: USA/ASIA (1)-206-881-6444 EUROPE (49)-8-985-8580

■ PROGRAMMING TO THE EPROM WITH PIGGYBACK/EVALUATION DEVICE

1. EPROM for Use

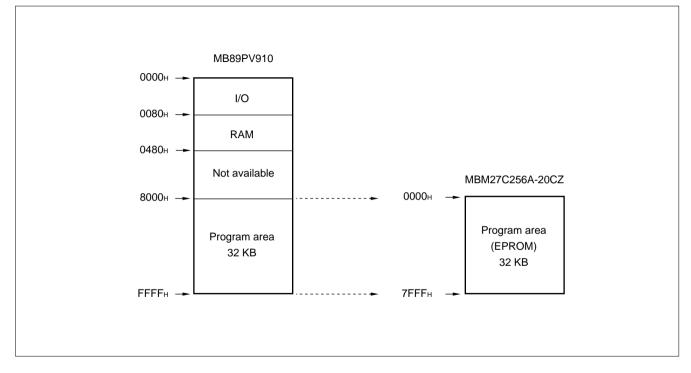
MBM27C256A-20CZ

2. Programming Socket Adapter

Any special programming adapter is not required since the package for the EPROM to be used is DIP-28.

3. Memory Space

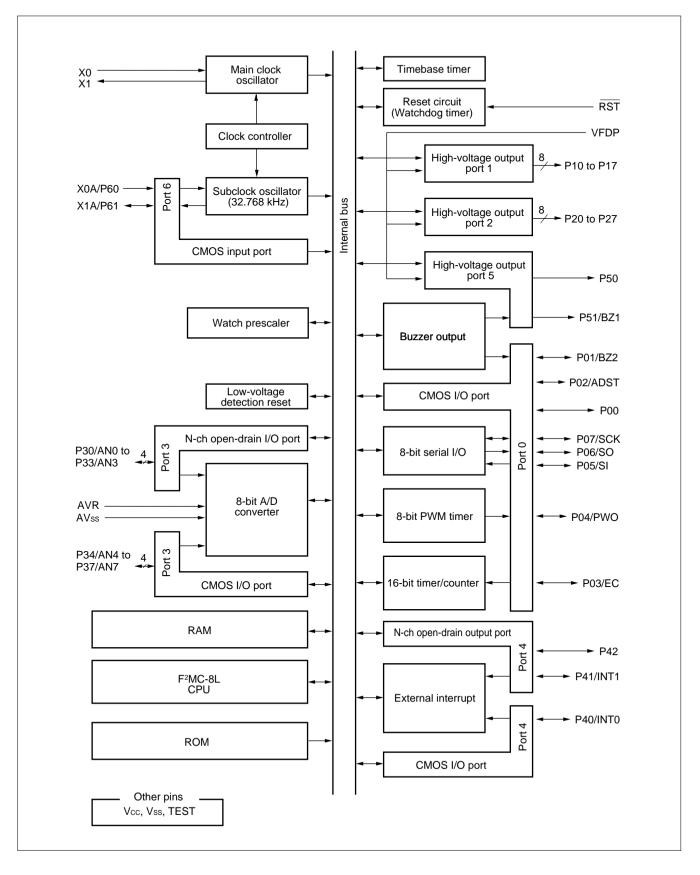
EPROM memory space and the memory space on the MB89PV910 are diagrammed below.



4. Programming to the EPROM

- (1) Set the EPROM programmer to the MBM27C256A-20CZ.
- (2) Load program data into the EPROM programmer at 0000H to 7FFFH. (note that addresses 08000H to 0FFFFH in the operation mode correspond to 0000H to 7FFFH in the EPROM mode.)
- (3) Program with the EPROM programmer.

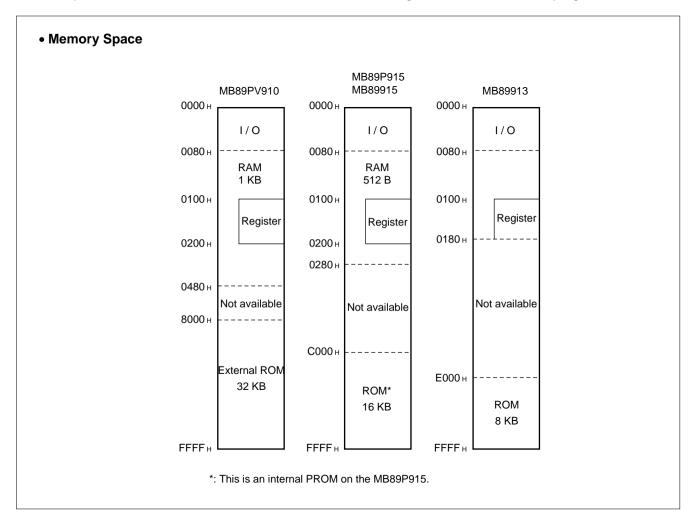
BLOCK DIAGRAM



CPU CORE

1. Memory Space

The microcontrollers of the MB89910 series offer a memory space of 64 Kbytes for storing all of I/O, data, and program areas. The I/O area is located the lowest address. The data area is provided immediately above the I/O area. The data area can be divided into register, stack, and direct areas according to the application. The program area is located at exactly the opposite end, that is, near the highest address. Provide the tables of interrupt reset vectors and vector call instructions toward the highest address within the program area.



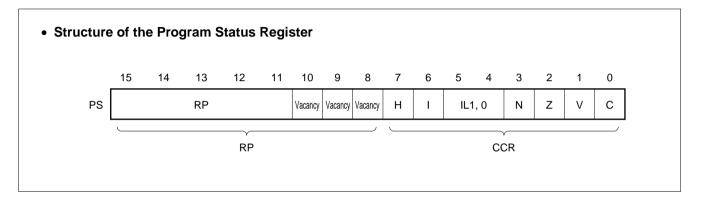
2. Registers

The F²MC-8L family has two types of registers; dedicated registers in the CPU and general-purpose registers in the memory. The following registers are provided:

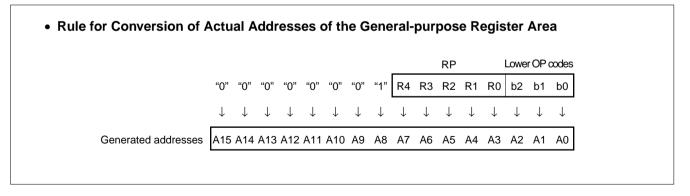
Program counter (PC):	A 16-bit register for indicating instruction storage positions
Accumulator (A):	A 16-bit temporary register for storing arithmetic operations, etc. When the instruction is an 8-bit data processing instruction, the lower byte is used.
Temporary accumulator (T):	A 16-bit register which performs arithmetic operations with the accumulator When the instruction is an 8-bit data processing instruction, the lower byte is used.
Index register (IX):	A 16-bit register for index modification
Extra pointer (EP):	A 16-bit pointer for indicating a memory address
Stack pointer (SP):	A 16-bit register for indicating a stack area
Program status (PS):	A 16-bit register for storing a register pointer, a condition code

◄ 16 bits →	Initial value
PC	: Program counter FFFD _H
A	: Accumulator Indeterminate
Т	: Temporary accumulator Indeterminate
IX	: Index register Indeterminate
EP	: Extra pointer Indeterminate
SP	: Stack pointer Indeterminate
PS	: Program status I-flag = 0, IL1, 0 = 11 The other bit values are indeterminat

The PS can further be divided into higher 8 bits for use as a register bank pointer (RP) and the lower 8 bits for use as a condition code register (CCR). (See the diagram below.)



The RP indicates the address of the register bank currently in use. The relationship between the pointer contents and the actual address is based on the conversion rule illustrated below.



The CCR consists of bits indicating the results of arithmetic operations and the contents of transfer data and bits for control of CPU operations at the time of an interrupt.

- H-flag: Set to '1' when a carry or a borrow from bit 3 to bit 4 occurs as a result of an arithmetic operation. Cleared to '0' otherwise. This flag is for decimal adjustment instructions.
- I-flag: Interrupt is enabled when this flag is set to '1'. Interrupt is disabled when the flag is cleared to '0'. Cleared to '0' at the reset.
- IL1, 0: Indicates the level of the interrupt currently allowed. Processes an interrupt only if its request level is higher than the value indicated by this bit.

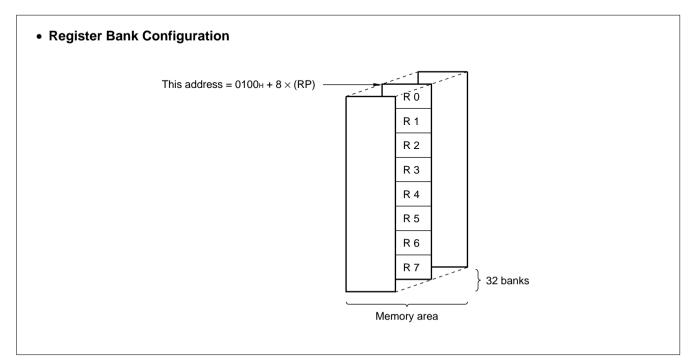
IL1	ILO	Interrupt level	High-low
0	0	1	High
0	1		ł
1	0	2	, ,
1	1	3	Low

- N-flag: Set to '1' if the MSB becomes to '1' as the result of an arithmetic operation. Cleared to '0' when the bit is cleared to '0'.
- Z-flag: Set to '1' when an arithmetic operation results in 0. Cleared to '0' otherwise.
- V-flag: Set to '1' if the complement on 2 overflows as a result of an arithmetic operation. Cleared to to '0' if the overflow does not occur.
- C-flag: Set to '1' when a carry or a borrow from bit 7 occurs as a result of an arithmetic operation. Cleared to '0' otherwise. Set to the shift-out value in the case of a shift instruction.

The following general-purpose registers are provided:

General-purpose registers: An 8-bit resister for storing data

The general-purpose registers are 8 bits and located in the register banks of the memory. One bank contains eight registers and up to a total of 32 banks can be used on the MB89915. The bank currently in use is indicated by the register bank pointer (RP).



■ I/O MAP

Address	Read/write	Register name	Register description
00н	(R/W)	PDR0	Port 0 data register
01н	(VV)	DDR0	Port 0 data direction register
02н			Vacancy
03н			Vacancy
04н			Vacancy
05н			Vacancy
06н			Vacancy
07н	(R/W)	SYCC	System clock control register
08н	(R/W)	STBC	Standby control register
09н	(R/W)	WDTC	Watchdog timer control register
0Ан	(R/W)	TBCR	Time-base timer control register
0Вн	(R/W)	WPCR	Watch prescaler control register
0Сн	(R/W)	PDR3	Port 3 data register
0Dн	(VV)	DDR3	Port 3 direction register
0Ен	(R/W)	BUZR	Buzzer register
0 F н	(R/W)	EIC	External interrupt control register
10н	(R/W)	PDR1	Port 1 data register
11н	(R/W)	PDR2	Port 2 data register
12н	(R/W)	PDR5	Port 5 data register
13н	(R)	PDR6	Port 6 data register
14 н	(R/W)	PDR4	Port 4 data register
15н	(VV)	DDR4	Port 4 direction register
16н	(VV)	COMR	PWM compare register
17 н	(R/W)	CNTR	PWM control register
18 н	(R/W)	TMCR	16-bit timer control register
19н	(R/W)	TCHR	16-bit timer control register (H)
1Ан	(R/W)	TCLR	16-bit timer control register (L)
1Bн		1	Vacancy
1Cн	(R/W)	SMR	Serial mode register
1Dн	(R/W)	SDR	Serial data register
1Eн	(R/W)	ADC1	A/D converter control register 1
1Fн	(R/W)	ADC2	A/D converter control register 2

(Continued)

Address	Read/write	Register name	Register description		
20н	(R/W)	ADCD	A/D converter data register		
21н			Vacancy		
22н	(W)	PCR	Port input control register		
23н	(R/W)	LVRC	Low-voltage detection reset control register		
24н to 7Вн			Vacancy		
7Cн	(W)	ILR1	Interrupt level setting register 1		
7Dн	(W)	ILR2	Interrupt level setting register 2		
7Eн	(W)	ILR3 Interrupt level setting register 3			
7 F н		-	Vacancy		

Note: Do not use vacancies.

■ ELECTRICAL CHARACTERISTICS

1. Absolute Maximum Ratings

(AVss = Vss = 0.0 V)

Demonster	Ourseland	Va	lue	11	Demerica
Parameter	Symbol	Min.	Max.	Unit	Remarks
	V _{cc} AVR	Vss-0.3	Vss + 7.0	V	AVR ≤ Vcc + 0.3*1
Power supply voltage	Vpp	- 0.6	13.0	V	
	VFDP	Vcc-40	Vcc + 0.3	V	
Input voltage	VI1	Vss-0.3	Vcc + 0.3	V	Except P41*2
	V _{I2}	Vss-0.3	7.0	V	P41
Output voltage	V ₀₁	Vss-0.3	Vcc + 0.3	V	Except P10 to P17, P20 to P27, P50, P51* ²
Oulput voltage	V ₀₂	Vcc-40.0	Vcc + 0.3	V	P10 to P17, P20 to P27 P50, P51
"H" level total maximum output current	ΣІон		-120	mA	
"H" level total average output current	ΣІонаν		-90	mA	Average value (operating current × operating rate)
			-12	mA	P00 to P07, P34 to P37, P40
"H" level maximum output current	Іон		-20	mA	P20 to P27, P50, P51
			-36	mA	P10 to P17
			-6	mA	P00 to P07, P34 to P37, P40 Average value (operating current × operating rate)
"H" level average output current	Іонач		-10	mA	P20 to P27, P50, P51 Average value (operating current \times operating rate)
			-20	mA	P10 to P17 Average value (operating current × operating rate)
"L" level total maximum output current	ΣΙοι		36	mA	
"L" level total average output current	ΣΙοιαν		20	mA	Average value (operating current × operating rate)
"L" level maximum output current	Iol		10	mA	P00 to P07, P30 to P37,
"L" level average output current	Iolav		— 4		P40 to P47

(Continued)

(AVss = Vss = 0.0 V)

Parameter	Symbol	Va	lue	Unit	Remarks
Farameter	Symbol	Min.	Max.	Unit	Reindiks
Power consumption	PD		440	mW	SH-DIP: DIP-48-M01
Power consumption	FD		360	mW	QFP: FPT-48-M15
Operating temperature	TA	-40	+85	°C	
Storage temperature	Tstg	-55	+150	°C	

*1: Take care so that AVR does not exceed Vcc+0.3 V and Vcc does not exceed Vcc, such as when power is turned on.

*2: VI and Vo must not exceed Vcc + 0.3 V.

WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

2. Recommended Operating Conditions

					(AVss = Vss = 0.0 V)
Parameter	Symbol	Va	lue	Unit	Remarks
Farameter	Symbol	Min.	Max.	Unit	Remarks
		4.5*	5.5*	V	Normal operation assurance range* (MB89PV910)
Power supply voltage	Vcc	3.8*	5.5*	V	Normal operation assurance range* (MB89P915/915/913)
		2.7	5.5	V	Watch mode, sub-RUN mode
		1.5	5.5	V	Retains the RAM state in stop mode
A/D converter reference input voltage	AVR	0.0	Vcc	V	
High-voltage pull-down resistor supply voltage	VFDP	Vcc-35.0	Vcc + 0.3	V	
Operating temperature	TA	-40	+85	°C	

* : These values vary with the operating frequency, instruction cycle, and analog assurance range. See Figure 1 and "5. A/D Converter Electrical Characteristics."

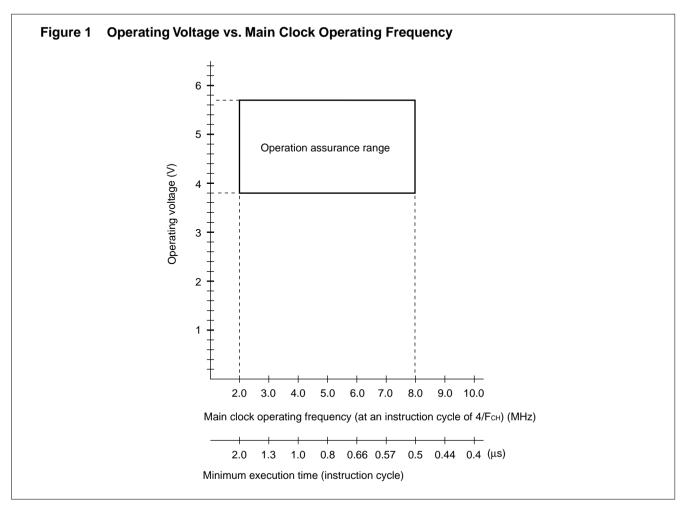


Figure 1 indicates the operating frequency of the external oscillator at an instruction cycle of 4/FcH.

Since the operating voltage range is dependent on the instruction cycle, see minimum execution time if the operating speed is switched using a gear.

WARNING: Recommended operating conditions are normal operating ranges for the semiconductor device. All the device's electrical characteristics are warranted when operated within these ranges.

Always use semiconductor devices within the recommended operating conditions. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their FUJITSU representative beforehand.

3. DC Characteristics

			1VA)	$\chi = \chi_{CC} = +5$	Value	s = vss = 0.	U V, 14	$a = -40^{\circ}C \text{ to } +85^{\circ}C$
Parameter	Symbol	Pin name	Condition	Min.	Typ.	Max.	Unit	Remarks
"H" level input voltage	Vihs	P00 to P07, P30 to P37, P40 to P42, P60, P61 X0, RST X1, TEST		0.8 Vcc	_	Vcc + 0.3	V	
"L" level input voltage	Vils	P00 to P07, P30 to P37, P40 to P42, P60, P61 X0, RST X1, TEST		Vss-0.3	_	0.2 Vcc	V	
Open-drain output pin	V _{D1}	P30 to P33, P42	_	Vss-0.3		Vcc + 0.3	V	
application voltage	V _{D2}	P41	_	Vss-0.3		7.0	V	
"H" level	Vон1	P00 to P07, P30 to P37, P40 to P42, P60, P61	Iон = −2.0 mA	2.4	_	_	V	Excluding P30 to P33 and P41, P42
output voltage	Vон2	P20 to P27, P50, P51	Іон = –10 mA	3.0	_	_	V	
	Vонз	P10 to P17	Іон = –20 mA	3.0	_		V	
"L" level output voltage	Vol1	P00 to P07, P30 to P37, P40 to P42, P60, P61	lo∟= 1.8 mA	_	_	0.4	V	
	Vol2	RST,	lo∟= 4.0 mA	_	—	0.6	V	
Input leakage current	ILII	P00 to P07, P30 to P37, P40 to P42, P60, P61	0 < Vi < Vcc	_	_	±5	μA	
Output leakage	ILO1	P20 to P27, P50, P51	VI = VFDP	_	_	-10	μA	VFDP = Vcc - 35.0 V
current	ILO2	P10 to P17	Vı = VFDP			-20	μA	VFDP = Vcc - 35.0 V
Pull-up resistance	Rpull	RST,	V _{IN} = 0.0 V	25	50	100	kΩ	
Pull-down resistance	Rpd	P10 to P17, P20 to P27, P50, P51	V _{IN} = 5.0 V	50	100	150	kΩ	Assuming the pull- down resistor option selected

(Continued)

			1	(AVR =	Vcc = +5.		= Vss = 0.	0 V, TA	$= -40^{\circ}$ C to $+85^{\circ}$
Parameter	Symbol	Pin name		Condition	Min.	Value Typ.	Max. Unit		Remarks
			Vc	H = 8 MHz c = 5.0 V		10.0	18.0	mA	MB89P915
	Icc1			$t^2 = 0.5 \ \mu s$ en A/D conversion stopped	_	9	15	mA	MB89913/ 915/PV910
	Icc2	-	$F_{CH} = 8 \text{ MHz}$ $V_{CC} = 3.8 \text{ V}$ $t_{inst}^{*2} = 8.0 \mu\text{s}$ when A/D conversion is stopped		_	3.0	6.0	mA	MB89P915
	ICC2				—	1.8	2.4	mA	MB89913/ 915/PV910
	Ics1		node	$F_{CH} = 8 \text{ MHz}$ $V_{CC} = 5.0 \text{ V}$ $t_{inst}^{*2} = 0.5 \mu\text{s}$ when A/D conversion is stopped	_	3	7	mA	
Power supply current ^{*1} When low-voltage detection reset operation is	Ics2	Vcc	Sleep mode	$F_{CH} = 8 \text{ MHz}$ $V_{CC} = 3.8 \text{ V}$ $t_{inst}^{*2} = 8.0 \mu\text{s}$ when A/D conversion is stopped	_	1.2	1.8	mA	
enabled, ILVD is added to each			_ = 32 kHz	—	1.2	3.6	mA	MB89P915	
current.	Ісѕв		Vcc = 3.0 V Subclock mo		_	60	180	μA	MB89913/ 915/PV910
	Ісѕз		Vc Su	L = 32 kHz c = 3.0 V bclock sleep ode	_	32	64	μA	
	Ісст		Vc • \ • N r	L = 32 kHz c = 3.0 V Watch mode Main clock stop node at dual- clock system		4	20	μΑ	
	Ісса		TA Vc tinst wh	H = 8 MHz = +25°C c = 5.0 V $t^2 = 0.5 \mu s$ en A/D conversion activated		12.5	22.5	mA	

(Continued)

Deremeter	Sumbel	Din nome	Condition		Value		Linit	Domortico
Parameter	Symbol	Pin name	Condition	Min.	Тур.	Max.	Unit	Remarks
Power supply current ^{*1} When low-voltage detection reset operation is enabled, ILVD is added to each power supply current.	Іссн	Vcc	F _{CL} = 32.678 kHz, V _{CC} = 3.0 V T _A = +25°C, • Subclock stop mode • Main clock stop mode at single clock system	_	_	10	μΑ	
	Ilvd		Vcc = 5.0 V T _A = +25°C, • Subclock stop mode • Main clock stop mode at single clock system	_	60	120	μΑ	Power consumption of low-voltage detection reset
	IR	AVR	$F_{CH} = 8 \text{ MHz},$ $T_A = +25^{\circ}\text{C},$ when A/D conversion is activated	_	200		μΑ	
	Irh	AVR	$F_{CH} = 8 \text{ MHz},$ $T_A = +25^{\circ}\text{C},$ when A/D conversion is stopped		_	10	μΑ	
Input capacitance	CIN	Other than AVss, AVR, Vcc, and Vss	f = 1 MHz	_	10		pF	

*1: The power supply current is measured at external clock.

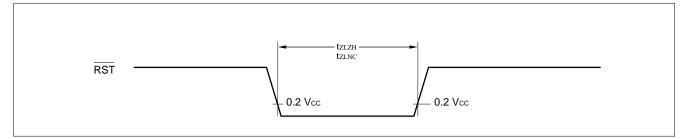
*2: For information on tinst, see "(4) Instruction Cycle" in "4. AC Characteristics."

4. AC Characteristics

(1) Reset Timing

$(AVR = V_{CC} = +5.0 V \pm 10\%, AV_{SS} = V_{SS} = 0.0 V, T_A = -40^{\circ}C \text{ to } +85^{\circ}C$									
Parameter	Symbol	I Condition		Value	Unit	Remarks			
	Symbol		Min.	Тур.	Max.	Unit	itema ka		
RST "L" pulse width	tzlzh	_	48 t xcyL	_	_	ns			
RST noise limit width	t ZLNC	_	30	50	80	ns			

Note: t_{XCYL} is the oscillation period (1/F_{CH}) to input to the X0.

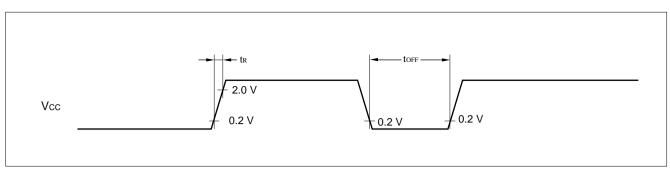


(2) Power-on Reset

 $(AV_{SS} = V_{SS} = 0.0 \text{ V}, T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C})$

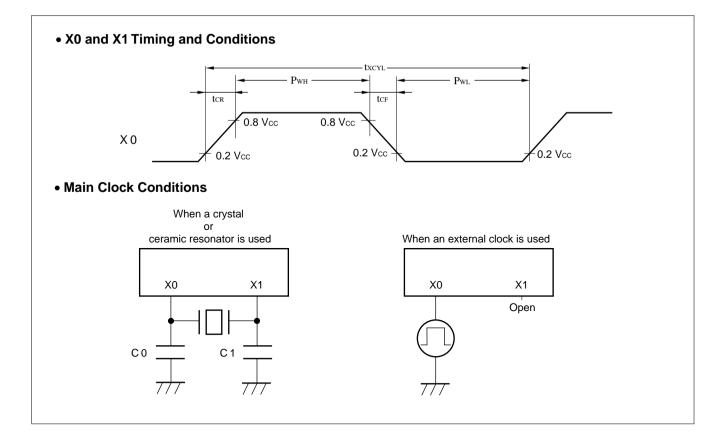
Parameter	Symbol	Condition	Va	lue	Unit	Remarks	
Farameter	Symbol	Condition	Min.	Max.	Unit	iteliai KS	
Power supply rising time	t R			50	ms	Power-on reset function only	
Power supply cut-off time	t off		1		ms	Due to repeated operations	

Note: Make sure that power supply rises within the selected oscillation stabilization time. If power supply voltage needs to be varied in the course of operation, a smooth voltage rise is recommended.

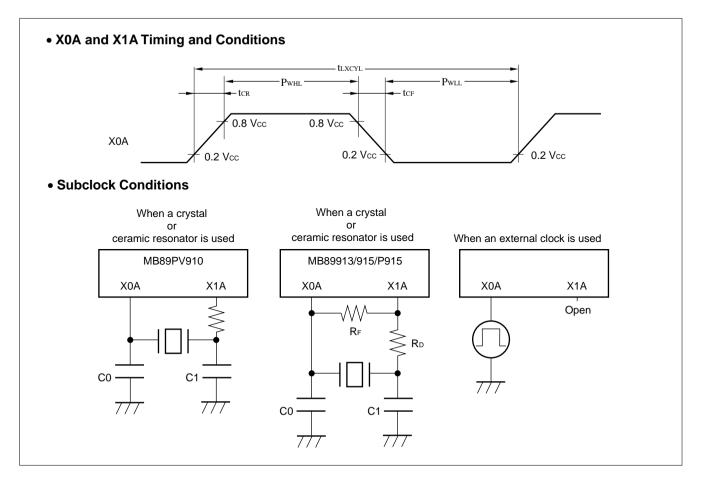


(3) Clock Timing

					Value			,
Parameter	Symbol	Pin name	Condition	Min.	Тур.	Max.	Unit	Remarks
	Fсн	X0, X1		2	—	8	MHz	
Clock frequency	Fc∟	X0A, X1A			32.768		kHz	
Clask svela time	txcyL	X0, X1		125		500	ns	
Clock cycle time	t LXCYL	X0A, X1A	_		30.5	_	μs	
Input clock pulse width	Р _{WH} PwL	X0	_	30	_	_	ns	External clock
Input clock pulse width	Pwhl Pwll	X0A	_	_	15.2	_	μs	
Input clock rising/falling time	tcr tcf	X0, X0A	_	_		10	ns	External clock



 $(AV_{SS} = V_{SS} = 0.0 \text{ V}, T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C})$



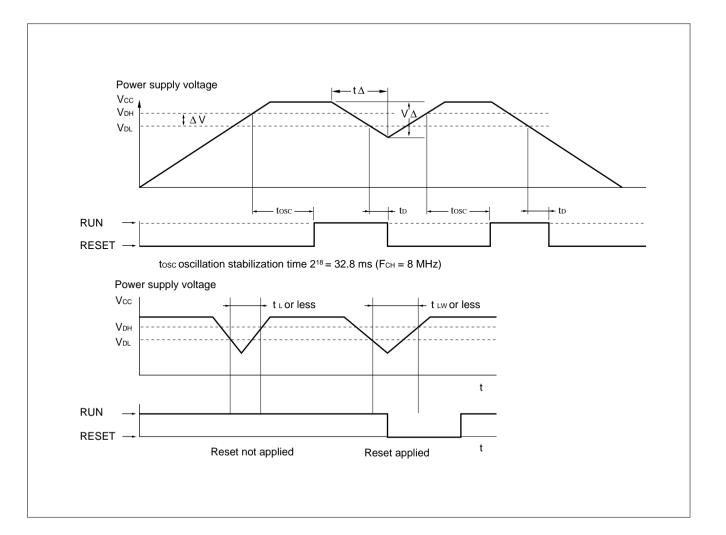
(4) Instruction Cycle

Parameter	Symbol	ol Value (typical)		Remarks
Instruction cycle (minimum execution time)	tinst	4/Fсн, 8/Fсн, 16/Fсн, 32/Fсн	μs	Operation at $F_{CH} = 8 \text{ MHz};$ (4/F _{CH}) $t_{inst} = 0.5 \ \mu s$
	Linst	2/Fc∟	μs	Operation at FcL = 32.768 kHz; (4/FcH)tinst = 61.036 μs

Note: When operating at 8 MHz, the cycle varies with the execution time.

(5) Low-voltage Detection Reset

$(AV_{SS} = V_{SS} 0.0 \text{ V}, \text{T}_{\text{A}} = -40^{\circ}\text{C} \text{ to } +85^{\circ}\text{C}$										
Parameter	Symbol	Condition	Valu	le	Unit	Remarks				
Farameter	Symbol	Condition	Min.	Max.	Unit	Nemarks				
	Vdl1	_	3.00	3.60	V					
Detection voltage at power supply voltage fall	Vdl2	—	3.30	3.90	V	VDH and VDL are set for				
	V _{DL3}		3.70	4.40	V	the MB89913/915 by mask options and for				
	V _{DH1}		3.10	3.80	V	the MB89P915 by a				
Detection voltage at power supply voltage rise	Vdh2	—	3.40	4.10	V	register.				
	Vdh3	_	3.80	4.60	V					
Hysteresis width	ΔV		0.10	—	V					
Reset insensitive time	t∟	—	0.3	—	μs					
Reset sensitive width	t∟w	—	16 txcy∟	_	ns					
Reset detection delay time	t⊳	—	—	2.0	μs					
Voltage regulation (V Δ /t Δ)	VCR		—	0.10	V/µs					

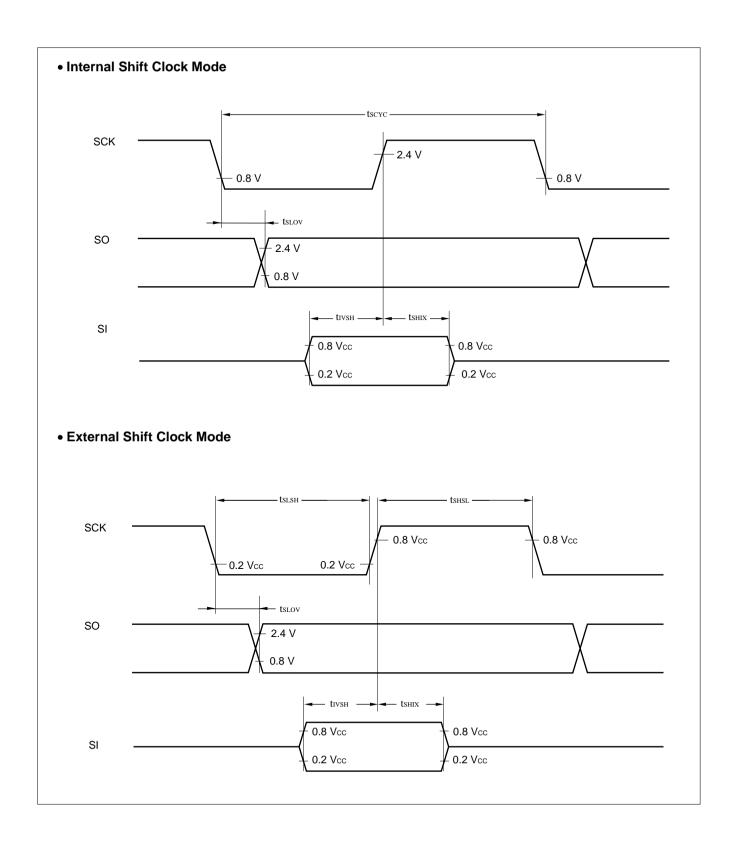


(6) Serial I/O Timing

Parameter	Symbol	Pin name	Condition	Value		Unit	Remarks
				Min.	Max.	Unit	Relliarks
Serial clock cycle time	tscyc	SCK	Internal shift clock mode	2 t _{inst} *	_	μs	
$SCK \downarrow \to SO$ time	tslov	SCK, SO		-200	200	ns	
Valid SI \rightarrow SCK \uparrow	tivsH	SI, SCK		1/2 t _{inst} *	_	μs	
SCK $\uparrow \rightarrow$ valid SI hold time	tsнıx	SCK, SI		1/2 t _{inst} *		μs	
Serial clock "H" pulse width	tshsl	SCK	External shift clock mode	1 t _{inst} *	_	μs	
Serial clock "L" pulse width	tslsh	SCK		1 tinst*	_	μs	
$SCK \downarrow \to SO$ time	tslov	SCK, SO		0	200	ns	
Valid SI \rightarrow SCK \uparrow	tıvsн	SI, SCK		1/2 t _{inst} *	_	μs	
$SCK \uparrow \to valid SI hold time$	tsнix	SCK, SI		1/2 t _{inst} *		μs	

(AVR = Vcc = +5.0 V±10%, AVss = Vss= 0.0 V, T_A = -40°C to +85°C)

* : For information on tinst, see "(4) Instruction Cycle."

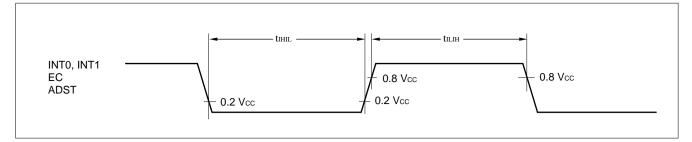


(7) Peripheral Input Timing

Demonster	Ourseland	Din mama	O a maliti a m	Val	ue	11	Demerles
Parameter	Symbol	Pin name	Condition	Min.	Max.	Unit	Remarks
Peripheral input "H" level pulse width	tilih	EC, ADST INT0, INT1		2 tinst*	_	μs	
Peripheral input "L" level pulse width	tihil	EC, ADST INT0, INT1		2 tinst*	_	μs	

 $(\Delta V/R - V/c_{0} - \pm 5.0)/(\pm 1.0\% - \Delta V/c_{0} - V/c_{0} - 0.0)/(T_{0} - -4.0\% - t_{0} \pm 85\%)$

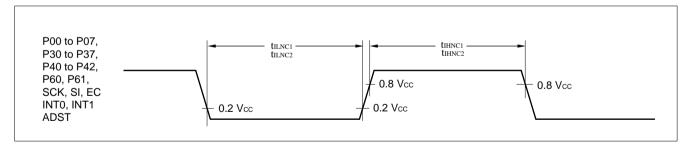
*: For information on tinst, see "(4) Instruction Cycle."



(8) Peripheral input noise limit width

		(AVR = Vcc = +	5.0 V±10	%, AVss=	Vss = 0.0) V, T _A =	–40°C to +85°C)
Parameter	Symbol	Pin name		Value		Unit	Remarks
Falanetei	Symbol	Fininanie	Min.	Тур.	Max.	Unit	itemaiks
Peripheral input "H" level	t _{IHNC1}	All inputs excluding	7	15	30	ns	MB89PV910 MB89P915
noise limit width 1	UHNC1	INT1 and INT0	15	30	60	ns	MB89913/ 915
Peripheral input "L" level	t u	All inputs excluding INT1 and INT0	7	15	30	ns	MB89PV910 MB89P915
noise limit width 1	tilnc1		15	30	60	ns	MB89913/ 915
Peripheral input "H" level	tunios	INT1, INT0	30	50	100	ns	MB89PV910 MB89P915
noise limit width 2	tihnc2		50	100	250	ns	MB89913/ 915
Peripheral input "L" level	tilnc2	INT1, INT0	30	50	100	ns	MB89PV910 MB89P915
noise limit width 2			50	100	250	ns	MB89913/ 915

Note: The minimum rating is always cancelled, while values equal to or greater than maximum ratings are not cancelled.



5. A/D Converter Electrical Characteristics

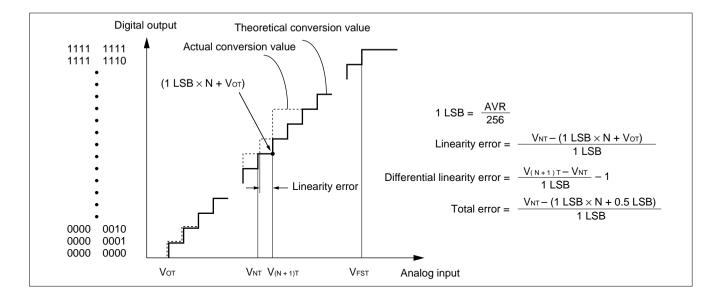
Parameter	Symbol	Pin name	Condition		Unit	Remarks		
Falameter	Symbol		Condition	Min.	Тур.	Max.	Unit	Rellians
Resolution				—	_	8	bit	
Total error				_	_	±3.0	LSB	
Linearity error		_		—	_	±1.0	LSB	
Differential linearity error				—	_	±0.9	LSB	
Zero transition voltage	Vот	AN0 to AN7		AVss – 1.5 LSB	AVss +0.5 LSB	AVss + 2.5 LSB	mV	
Full-scale transition voltage	VFST	AN0 to AN7		AVR-3.5 LSB	AVR-1.5LSB	AVR +0.5 LSB	mV	
Interchannel disparity				_	_	1.0	LSB	
A/D mode conversion time	1			—	44 tinst*		μs	
Sense mode conversion time				_	12 t _{inst} *	_	μs	
Analog port input current	lain	AN0 to AN7	AVR = Vcc = 5.0 V	—	—	10	μA	
Analog input voltage		AN0 to AN7		0.0	_	AVR	V	
Reference voltage	-	AVR		3.4	—	AVcc	V	
Reference voltage supply current	Ir	AVR	AVR = 5.0 V	_	200	—	μA	

(Vcc = +3.8 V to +5.5 V, F = 8 MHz, AVss = Vss = 0.0 V, T_A = -40°C to +85°C)

* : For information on tinst, see "(4) Instruction Cycle" in "4. AC Characteristics."

6. A/D Converter Glossary

- Resolution
 Analog changes that are identifiable with the A/D converter
 When the number of bits is 8, analog voltage can be divided into 2⁸ = 256.
- Linearity error (unit: LSB) The deviation of the straight line drawn connecting the zero transition point ("0000 0000 " ↔ "0000 0001") with the full-scale transition point ("1111 1111 " ↔ "1111 1110") from actual conversion characteristics
- Differential linearity error (unit: LSB)
 The deviation of input voltage needed to change the output code by 1 LSB from the theoretical value
- Total error (unit: LSB)
 The difference between theoretical and actual conversion values



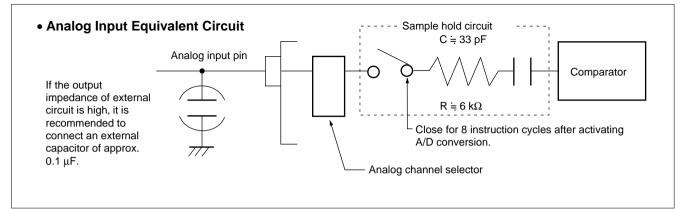
7. Notes on Using A/D Converter

· Input impedance of the analog input pins

The A/D converter used for the MB89910 series contains a sample hold circuit as illustrated below to fetch analog input voltage into the sample hold capacitor for eight instruction cycles after activating A/D conversion.

For this reason, if the output impedance of the external circuit for the analog input is high, analog input voltage might not stabilize within the analog input sampling period. Therefore, it is recommended to keep the output impedance of the external circuit low. If a higher accurancy is required, set the output impedance in this series to 2 k Ω or less.

Note that if the impedance cannot be kept low output impedance, it is recommended either to use the software to continuously activate the A/D converter for simulating longer sampling time or to connect an external capacitor of approx. 0.1 μ F to the analog input pin.

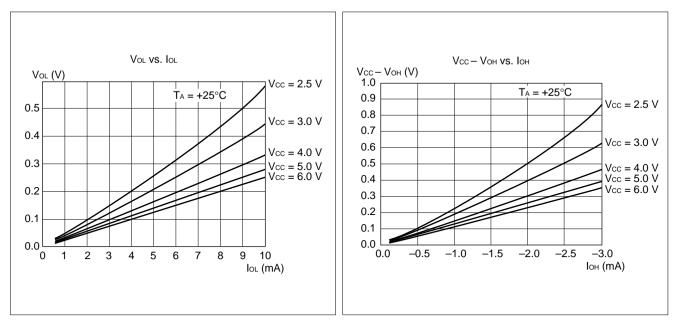


• Error

The smaller the | AVR - AVss |, the greater the error would become relatively.

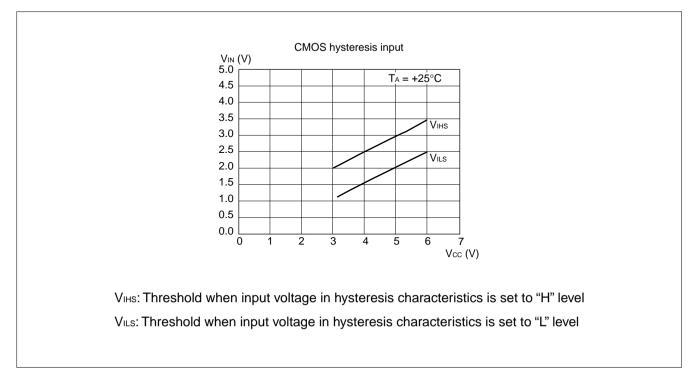
■ EXAMPLE CHARACTERISTICS

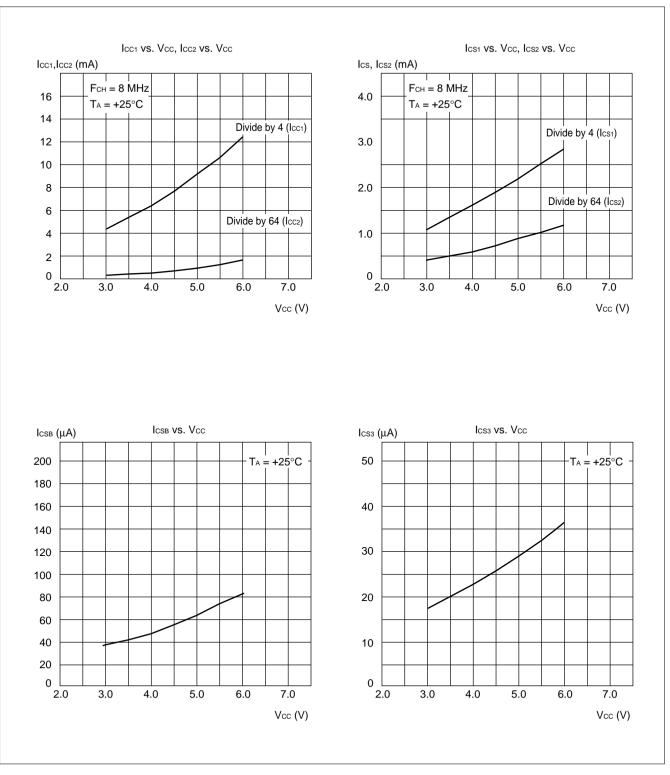
(1) "L" Level Output Voltage



(2) "H" Level Output Voltage

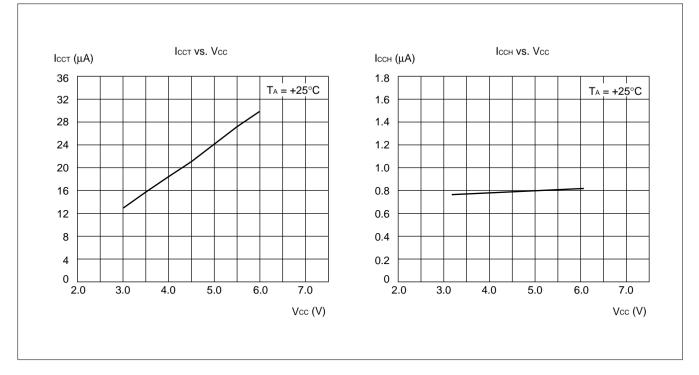
(3) "H" Level Input Voltage/"L" Level Input Voltage (Hysteresis Input)



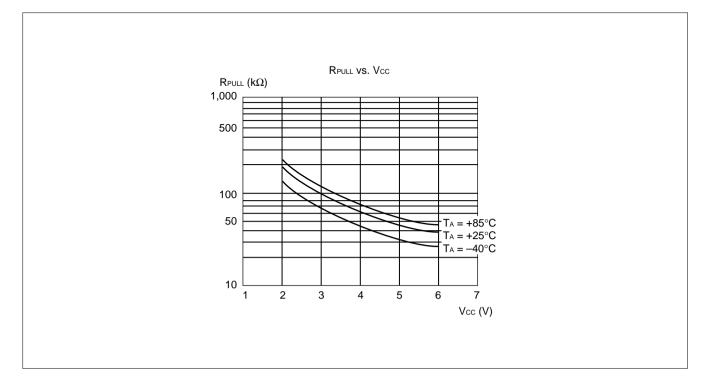


(4) Power Supply Current (External Clock)

(Continued)



(5) Pull-up Resistance



■ INSTRUCTIONS

Execution instructions can be divided into the following four groups:

- Transfer
- Arithmetic operation
- Branch
- Others

Table 1 lists symbols used for notation of instructions.

Symbol	Meaning
dir	Direct address (8 bits)
off	Offset (8 bits)
ext	Extended address (16 bits)
#vct	Vector table number (3 bits)
#d8	Immediate data (8 bits)
#d16	Immediate data (16 bits)
dir: b	Bit direct address (8:3 bits)
rel	Branch relative address (8 bits)
@	Register indirect (Example: @A, @IX, @EP)
A	Accumulator A (Whether its length is 8 or 16 bits is determined by the instruction in use.)
AH	Upper 8 bits of accumulator A (8 bits)
AL	Lower 8 bits of accumulator A (8 bits)
Т	Temporary accumulator T (Whether its length is 8 or 16 bits is determined by the instruction in use.)
ТН	Upper 8 bits of temporary accumulator T (8 bits)
TL	Lower 8 bits of temporary accumulator T (8 bits)
IX	Index register IX (16 bits)

Table 1 Instruction Symbols

(Continued)

Symbol	Meaning
EP	Extra pointer EP (16 bits)
PC	Program counter PC (16 bits)
SP	Stack pointer SP (16 bits)
PS	Program status PS (16 bits)
dr	Accumulator A or index register IX (16 bits)
CCR	Condition code register CCR (8 bits)
RP	Register bank pointer RP (5 bits)
Ri	General-purpose register Ri (8 bits, i = 0 to 7)
×	Indicates that the very \times is the immediate data. (Whether its length is 8 or 16 bits is determined by the instruction in use.)
(×)	Indicates that the contents of \times is the target of accessing. (Whether its length is 8 or 16 bits is determined by the instruction in use.)
((×))	The address indicated by the contents of \times is the target of accessing. (Whether its length is 8 or 16 bits is determined by the instruction in use.)

Columns indicate the following:

Mnemonic:	Assembler notation of an instruction
~:	Number of instructions
#:	Number of bytes
Operation:	Operation of an instruction
TL, TH, AH:	A content change when each of the TL, TH, and AH instructions is executed. Symbols in the column indicate the following:
	 "-" indicates no change. dH is the 8 upper bits of operation description data. AL and AH must become the contents of AL and AH immediately before the instruction is executed. 00 becomes 00.
N, Z, V, C:	An instruction of which the corresponding flag will change. If + is written in this column, the relevant instruction will change its corresponding flag.
OP code:	Code of an instruction. If an instruction is more than one code, it is written according to the following rule:
	Example: 48 to $4F \leftarrow$ This indicates 48, 49, 4F.

Mnemonic	~	#	Operation	TL	TH	AH	NZVC	OP code
MOV dir,A	3	2	$(dir) \leftarrow (A)$	_	_	_		45
MOV @IX +off,A	4	2	$((IX) + off) \leftarrow (A)$	_	_	_		46
MOV ext,A	4	3	$(ext) \leftarrow (A)$	_	_	_		61
MOV @EP,A	3	1	$((EP)) \leftarrow (A)$	_	_	_		47
MOV Ri,A	3	1	$(\dot{Ri}) \leftarrow (A)$	_	_	_		48 to 4F
MOV A,#d8	2	2	$(A) \leftarrow dB'$	AL	_	_	++	04
MOV A,dir	3	2	$(A) \leftarrow (dir)$	AL	_	_	++	05
MOV A,@IX +off	4	2	$(A) \leftarrow ((IX) + off)$	AL	_	_	++	06
MOV A,ext	4	3	$(A) \leftarrow (ext)$	AL	_	_	++	60
MOV A,@A	3	1	$(A) \leftarrow (A)$	AL	_	_	++	92
MOV A,@EP	3	1	$(A) \leftarrow ((EP))$	AL	_	_	++	07
MOV A,Ri	3	1	$(A) \leftarrow (Ri)$	AL	_	_	++	08 to 0F
MOV dir,#d8	4	3	$(dir) \leftarrow d8$	_	_	_		85
MOV @IX +off,#d8	5	3	$((IX) + off) \leftarrow d8$	_	_	_		86
MOV @EP,#d8	4	2	$((EP)) \leftarrow d8$	_	_	_		87
MOV Ri,#d8	4	2	$(Ri) \leftarrow d8$	_	_	_		88 to 8F
MOVW dir,A	4	2	$(dir) \leftarrow (AH), (dir + 1) \leftarrow (AL)$	_	_	_		D5
MOVW @IX +off,A	5	2	$((IX) + off) \leftarrow (AH),$	_	_	_		D6
		-	$((IX) + off + 1) \leftarrow (AL)$					50
MOVW ext,A	5	3	$(ext) \leftarrow (AH), (ext + 1) \leftarrow (AL)$	_	_	_		D4
MOVW @EP,A	4	1	$((EP)) \leftarrow (AH), ((EP) + 1) \leftarrow (AL)$	_	_	_		D7
MOVW EP,A	2	1	$(EP) \leftarrow (A)$	_	_	_		E3
MOVW A,#d16	3	3	$(A) \leftarrow d16$	AL	AH	dH	++	E4
MOVW A,dir	4	2	$(AH) \leftarrow (dir), (AL) \leftarrow (dir + 1)$	AL	AH	dH	++	C5
MOVW A,@IX +off	5	2	$(AH) \leftarrow ((IX) + off),$	AL	AH	dH	++	C6
		-	$(AL) \leftarrow ((IX) + off + 1)$	/\L	/			00
MOVW A,ext	5	3	$(AH) \leftarrow (ext), (AL) \leftarrow (ext + 1)$	AL	AH	dH	++	C4
MOVW A,@A	4	1	$(AH) \leftarrow ((A)), (AL) \leftarrow ((A)) + 1)$	AL	AH	dH	++	93
MOVW A,@EP	4	1	$(AH) \leftarrow ((EP)), (AL) \leftarrow ((EP) + 1)$	AL	AH	dH	· · ·	C7
MOVW A, CP	2	1	$(A) \leftarrow (EP)$	7L _		dH		F3
MOVW EP,#d16	3	3	$(EP) \leftarrow d16$	_	_	_		E7
MOVW IX,A	2	1	$(IX) \leftarrow (A)$	_	_	_		E2
MOVW A,IX	2	1	$(A) \leftarrow (IX)$	_	_	dH		F2
MOVW SP,A	2	1	$(SP) \leftarrow (A)$	_	_	_		E1
MOVW A,SP	2	1	$(A) \leftarrow (SP)$	_	_	dH		F1
MOV @A,T	3	1	$((A)) \leftarrow (T)$	_	_	_		82
MOVW @A,T	4	1	$((A)) \leftarrow (TH), ((A) + 1) \leftarrow (TL)$	_	_	_		83
MOVW IX,#d16	3	3	$(IX) \leftarrow d16$	_	_	_		E6
MOVW A,PS	2	1	$(A) \leftarrow (PS)$	_	_	dH		70
MOVW PS,A	2	1	$(PS) \leftarrow (A)$	_	_	_	++++	71
MOVW SP,#d16	3	3	$(SP) \leftarrow d16$	_	_	_		E5
SWAP	2	1	$(AH) \leftrightarrow (AL)$	_	_	AL		10
SETB dir: b	4	2	(dir): $b \leftarrow 1$	_	_			A8 to AF
CLRB dir: b	4	2	(dir): $b \leftarrow 0$	_	_	_		A0 to A7
XCH A,T	2	1	$(AL) \leftrightarrow (TL)$	AL	_	_		42
XCHW A,T	3	1	$(A) \leftrightarrow (T)$	AL	AH	dH		43
XCHW A,EP	3	1	$(A) \leftrightarrow (EP)$	_		dH		43 F7
XCHW A,IX	3	1	$(A) \leftrightarrow (IX)$	_		dH		F6
XCHW A,SP	3	1	$(A) \leftrightarrow (SP)$	_		dH		F5
MOVW A,PC	2	1	$(A) \leftrightarrow (OC)$ $(A) \leftarrow (PC)$	_	_	dH		F0
	_							10

Notes: • During byte transfer to A, T ← A is restricted to low bytes.
• Operands in more than one operand instruction must be stored in the order in which their mnemonics are written. (Reverse arrangement of F²MC-8 family)

Mnemonic	~	#	Operation	TL	TH	AH	NZVC	OP code
ADDC A,Ri	3	1	$(A) \leftarrow (A) + (Ri) + C$	_	_	_	++++	28 to 2F
ADDC A,#d8	2	2	$(A) \leftarrow (A) + d8 + C$	_	_	-	++++	24
ADDC A,dir	3	2	$(A) \leftarrow (A) + (dir) + C$	_	_	_	++++	25
ADDC A,@IX +off	4	2	$(A) \leftarrow (A) + ((IX) + off) + C$	_	_	-	++++	26
ADDC A,@EP	3	1	$(A) \leftarrow (A) + ((EP)) + C$	_	_	-	++++	27
ADDCWA	3	1	$(A) \leftarrow (A) + (T) + C$	_	_	dH	++++	23
ADDC A	2	1	$(AL) \leftarrow (AL) + (TL) + C$	_	_	-	++++	22
SUBC A,Ri	3	1	$(A) \leftarrow (A) - (Ri) - C$	-	_	-	++++	38 to 3F
SUBC A,#d8	2	2	$(A) \leftarrow (A) - dB - C$	_	_	-	++++	34
SUBC A,dir	3	2	$(A) \leftarrow (A) - (dir) - C$	_	_	-	++++	35
SUBC A,@IX +off	4	2	$(A) \leftarrow (A) - ((IX) + off) - C$	-	_	_	++++	36
SUBC A,@EP	3	1	$(A) \leftarrow (A) - ((EP)) - C$	-	_	_	++++	37
SUBCW A	3	1	$(A) \leftarrow (T) - (A) - C$	-	_	dH	++++	33
SUBC A	2	1	$(AL) \leftarrow (TL) - (AL) - C$	-	_	_	++++	32
INC Ri	4	1	$(Ri) \leftarrow (Ri) + 1$	-	_	_	+++-	C8 to CF
INCW EP	3	1	$(EP) \leftarrow (EP) + 1$	-	_	_		C3
INCW IX	3	1	$(IX) \leftarrow (IX) + 1$	-	_	-		C2
INCW A	3	1	(A) ← (A) + 1	-	_	dH	++	C0
DEC Ri	4	1	$(Ri) \leftarrow (Ri) - 1$	-	_	-	+++-	D8 to DF
DECW EP	3	1	$(EP) \leftarrow (EP) - 1$	-	_	-		D3
DECW IX	3	1	$(IX) \leftarrow (IX) - 1$	-	_	-		D2
DECW A	3	1	$(A) \leftarrow (A) - 1$	-	_	dH	++	D0
MULU A	19	1	$(A) \leftarrow (AL) \times (TL)$	-	_	dH		01
DIVU A	21	1	$(A) \leftarrow (T) / (AL), MOD \rightarrow (T)$	dL	00	00		11
ANDW A	3	1	$(A) \leftarrow (A) \land (T)$	-	-	dH	+ + R –	63
ORW A	3	1	$(A) \leftarrow (A) \lor (T)$	-	—	dH	+ + R –	73
XORW A	3	1	$(A) \leftarrow (A) \forall (A)$	-	—	dH	+ + R –	53
CMP A	2	1	(TL) – (AL)	-	—	-	++++	12
CMPW A	3	1	(T) – (A)	-	-	-	++++	13
RORC A	2	1	ightarrow C ightarrow A	-	_	-	+ + - +	03
ROLC A	2	1	$-C \leftarrow A \leftarrow$	-	_	-	++-+	02
CMP A,#d8	2	2	(A) – d8	_	_	_	++++	14
CMP A,dir	3	2	(A) – (dir)	-	_	_	++++	15
CMP A,@EP	3	1	(A) – ((EP))	-	_	_	++++	17
CMP A,@IX +off	4	2	(A) – ((IX) +off)	-	_	_	++++	16
CMP A,Ri	3	1	(A) – (Ri)	-	_	_	++++	18 to 1F
DAA	2	1	Decimal adjust for addition	-	_	_	++++	84
DAS	2	1	Decimal adjust for subtraction	-	_	_	++++	94
XOR A	2	1	$(A) \leftarrow (AL) \forall (TL)$	-	_	_	+ + R –	52
XOR A,#d8	2	2	$(A) \leftarrow (AL) \; \forall \; d8$	-	_	_	+ + R –	54
XOR A,dir	3	2	$(A) \leftarrow (AL) \forall (dir)$	-	_	-	+ + R –	55
XOR A,@EP	3	1	$(A) \leftarrow (AL) \; \forall \; (\; (EP) \;)$	-	_	-	++R-	57
XOR A,@IX +off	4	2	$(A) \leftarrow (AL) \forall ((IX) + off)$	-	_	_	+ + R –	56
XOR A,Ri	3	1	$(A) \leftarrow (AL) \forall (Ri)$	-	-	-	+ + R –	58 to 5F
AND A	2	1	$(A) \leftarrow (AL) \land (TL)$	-	-	-	+ + R –	62
AND A,#d8	2	2	$(A) \leftarrow (AL) \land d8$	-	-	-	+ + R –	64
AND A,dir	3	2	$(A) \leftarrow (AL) \land (dir)$	-		-	+ + R –	65
								(Continued)

 Table 3
 Arithmetic Operation Instructions (62 instructions)

Mnemonic	~	#	Operation	TL	TH	AH	NZVC	OP code
AND A,@EP	3	1	$(A) \leftarrow (AL) \land ((EP))$	_	_	_	+ + R –	67
AND A,@IX +off	4	2	$(A) \leftarrow (AL) \land ((IX) + off)$	_	_	-	++R-	66
AND A,Ri	3	1	$(A) \leftarrow (AL) \land (Ri)$	_	_	-	++R-	68 to 6F
OR A	2	1	$(A) \leftarrow (AL) \lor (TL)$	_	_	_	++R-	72
OR A,#d8	2	2	$(A) \leftarrow (AL) \lor d8$	_	_	-	+ + R –	74
OR A,dir	3	2	$(A) \leftarrow (AL) \lor (dir)$	_	_	-	++R-	75
OR A,@EP	3	1	$(A) \leftarrow (AL) \lor ((EP))$	_	_	-	+ + R –	77
OR A,@IX +off	4	2	$(A) \leftarrow (AL) \lor ((IX) + off)$	_	_	-	++R-	76
OR A,Ri	3	1	$(A) \leftarrow (AL) \lor (Ri)$	_	_	_	++R-	78 to 7F
CMP dir,#d8	5	3	(dir) – d8	_	_	-	++++	95
CMP @EP,#d8	4	2	((EP)) – d8	_	_	-	++++	97
CMP @IX +off,#d8	5	3	((IX) + off) - d8	_	_	_	++++	96
CMP Ri,#d8	4	2	(Ri) – d8	_	_	-	++++	98 to 9F
INCW SP	3	1	$(SP) \leftarrow (SP) + 1$	—	_	-		C1
DECW SP	3	1	$(SP) \leftarrow (SP) - 1$	-	—	_		D1

Mnemonic	~	#	Operation	TL	TH	AH	NZVC	OP code
BZ/BEQ rel	3	2	If Z = 1 then PC \leftarrow PC + rel	_	_	_		FD
BNZ/BNE rel	3	2	If Z = 0 then PC \leftarrow PC + rel	_	_	_		FC
BC/BLO rel	3	2	If C = 1 then PC \leftarrow PC + rel	—	_	-		F9
BNC/BHS rel	3	2	If C = 0 then PC \leftarrow PC + rel	—	_	-		F8
BN rel	3	2	If N = 1 then PC \leftarrow PC + rel	—	_	-		FB
BP rel	3	2	If N = 0 then PC \leftarrow PC + rel	—	_	-		FA
BLT rel	3	2	If V \forall N = 1 then PC \leftarrow PC + rel	—	_	-		FF
BGE rel	3	2	If V \forall N = 0 then PC \leftarrow PC + rel	—	_	-		FE
BBC dir: b,rel	5	3	If (dir: b) = 0 then PC \leftarrow PC + rel	—	_	-	-+	B0 to B7
BBS dir: b,rel	5	3	If (dir: b) = 1 then PC \leftarrow PC + rel	—	_	-	-+	B8 to BF
JMP @A	2	1	$(PC) \leftarrow (A)$	—	_	-		E0
JMP ext	3	3	$(PC) \leftarrow ext$	—	_	-		21
CALLV #vct	6	1	Vector call	—	_	-		E8 to EF
CALL ext	6	3	Subroutine call	—	_	-		31
XCHW A,PC	3	1	$(PC) \leftarrow (A), (A) \leftarrow (PC) + 1$	-	-	dH		F4
RET	4	1	Return from subrountine	-	-	_		20
RETI	6	1	Return form interrupt	-	—	-	Restore	30

Table 5	Other	Instructions ((9	instructions)	
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Mnemonic	~	#	Operation	TL	TH	AH	NZVC	OP code
PUSHW A	4	1		_	_	_		40
POPW A	4	1		_	_	dH		50
PUSHW IX	4	1		_	_	-		41
POPW IX	4	1		_	_	-		51
NOP	1	1		_	_	-		00
CLRC	1	1		_	_	-	––– R	81
SETC	1	1		_	_	-	S	91
CLRI	1	1		_	_	_		80
SETI	1	1		—	_	_		90

	LH	0	1	2	3	4	5	9	7	8	6	A	В	ပ	۵	ш	ш
	0	NOP	SWAP	RET	RETI	PUSHW			NOM	CLRI	SETI	CLRB dir:0	В		DECW A	JMP @A	MOVW A,PC
	-		DIVU	Σſ	C C	PUSHW			MOW PS,A		SETC	CLRB dir: 1	BBC dir: 1,rel		DECW SP	MOVW SP,A	MOVW A,SP
RORC CURW ADDCW SUBCW XCHW ADDW MOW MOW CURB BBC III MOV Aprile Aprile Aprile Aprile Aprile Aprile Aprile BBC BBC <td< th=""><th>7</th><th></th><th>CMP</th><th></th><th></th><th></th><th></th><th></th><th></th><th>MOV @A,T</th><th>MOV A,@A</th><th>CLRB dir: 2</th><th>В</th><th></th><th>DECW</th><th>MOVW IX,A</th><th>MOVW A,IX</th></td<>	7		CMP							MOV @A,T	MOV A,@A	CLRB dir: 2	В		DECW	MOVW IX,A	MOVW A,IX
	с		CMPW	ADDCW A	⊿	XCHW A, T	XORW			MON	MOWV A,@A	CLRB dir: 3	BI		DECW EP	MOVW EP,A	MOVW A,EP
	4	MOV A,#d8	CM	ADI	SUE		XOR A,#d8	ANE			DAS	CLRB dir: 4	B	MOWV A,ext	MOVW ext,A	MOVW A,#d16	XCHW A,PC
MOVMOVADDCADDCADDCADDCADDCADDCADDCADDCADDCADDCADDCBDCADDCBDCADDCBDCADDCBDCADDCBDCADDCBDCADDCADDCBDCADDCADDCBDCADDCADDCBDCADDCADDCBDCADDCADDCBDCADDCADDCBDCAD	5	MOV A,dir	CMP	ADD	SUB(AND		M	CMP dir,#d8	CLRB dir: 5	В	MOM	MOVW dir,A	MOVW SP,#d16	XCHW A,SP
MOVMOVSUBCMOV	Q	MOV A,@IX +d			SUBC A,@lX +d	MOV @IX +d,A	XOR @A,IX +d	AND A,@IX +d	OR A,@IX +d	MOV @IX +d,#d8	CMP @IX +d,#d8	CLRB dir:6	B		MOVW @IX +d,A	MOVW IX,#d16	XCHW A,IX
MOVMOVCMPADDCSUBCMOVXORANDANDANDBBSINCMOVROARDARDROROARD </th <th>7</th> <th>MOV A,@EP</th> <th>5</th> <th>AI</th> <th>SI</th> <th>ž</th> <th>XOR A,@EP</th> <th>A</th> <th>5</th> <th></th> <th>CMP @EP,#d8</th> <th>CLRB dir: 7</th> <th>BBC dir: 7,rel</th> <th>MOVW A,@EP</th> <th>MOVW @EP,A</th> <th>MOVW EP,#d16</th> <th>XCHW A,EP</th>	7	MOV A,@EP	5	AI	SI	ž	XOR A,@EP	A	5		CMP @EP,#d8	CLRB dir: 7	BBC dir: 7,rel	MOVW A,@EP	MOVW @EP,A	MOVW EP,#d16	XCHW A,EP
MOVMOVMDCMDCSUBCMOVNCHARIARIARIARIBISBISMILARIARIARIARIARIARIARIARIARIARIBISdir: 1ddir: 2ddir: 2d	œ	MOV A,R0	CMP A,R0	ADD	SUBC A,R0		XOR	AND A,R0		ž	CMP R0,#d8	SETB dir: 0	B		DEC R0	CALLV #0	BNC rel
MOV DMOV ARZBADC ARZSUBC ARZMOV A	6	MOV A,R1	CMP	ADD	SUBC A,R1		XOR	AND A,R1		ž	CMP R1,#d8	SETB dir: 1	BBS dir: 1,rel		DEC R1	CALLV #1	BC rel
MOV A_{AR3} MOV A_{AR3} SUBC A_{AR3} MOV A_{R3} MOV A_{R3} MOV A_{R3} SETB A_{R3} BS S A_{R3} INCMOV	٩	MOV A,R2	CMP	ADD	SUBC A,R2		XOR A,R2	AND A,R2		ž	ъ С	SETB dir: 2	В	INC	DEC R2	CALLV #2	BP rel
MOV $A,R4$ MOV $A,R4$ SUBC $A,R4$ MOV $A,R4$ MOV 	8	MOV A,R3	CMP	ADD	SUB		XOR A,R3			M	CMP R3,#d8	SETB dir: 3	BI	INC	DEC R3	CALLV #3	BN rel
	ပ	MOV A,R4	CMP	ADD	SUBC A,R4		XOR A,R4	AND A,R4		M	CMP R4,#d8	SETB dir: 4	BE		DEC R4	CALLV #4	BNZ rel
MOV MOV ADDC SUBC MOV XOR MOV CMP SETB BBS INC MAR A,R6 A,R6 A,R6 A,R6 A,R6 A,R6 B1 B1 B1 MOV A,R6 A,R6 A,R6 A,R6 A,R6 B1 B1 B1 MOV CMP ADC SUBC MOV XOR A,R7	۵	MOV A,R5	CMP	ADD	SUBC A,R5		XOR A,R5	and A,R5		ž	CMP R5,#d8	SETB dir: 5	В		DEC R5	CALLV #5	BZ rel
MOV CMP ADDC SUBC MOV XOR AND OR MOV CMP SETB BBS INC A,R7	ш	MOV A,R6	CMP	ADD	SUBC A,R6		XOR	AND		M	CMP R6,#d8	SETB dir: 6	BI		DEC R6	CALLV #6	BGE rel
	ш	MOV A,R7	CMP	ADDC A,R7	SUBC A,R7		XOR	AND		ž	5	SETB dir: 7	B	INC	DEC R7	CALLV #7	BLT rel

■ INSTRUCTION MAP

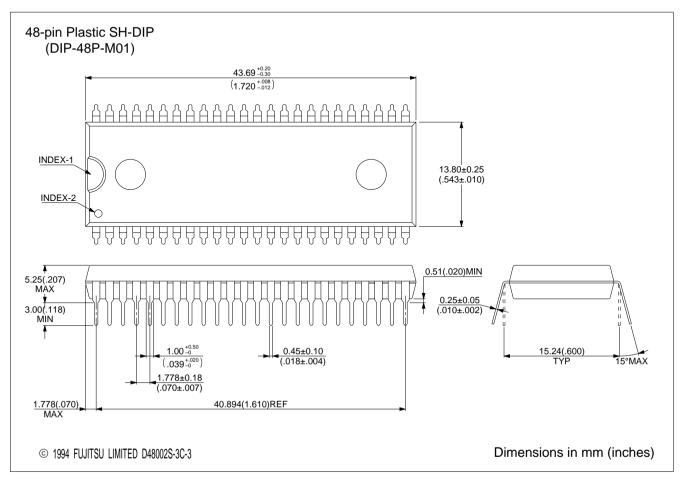
■ MASK OPTIONS

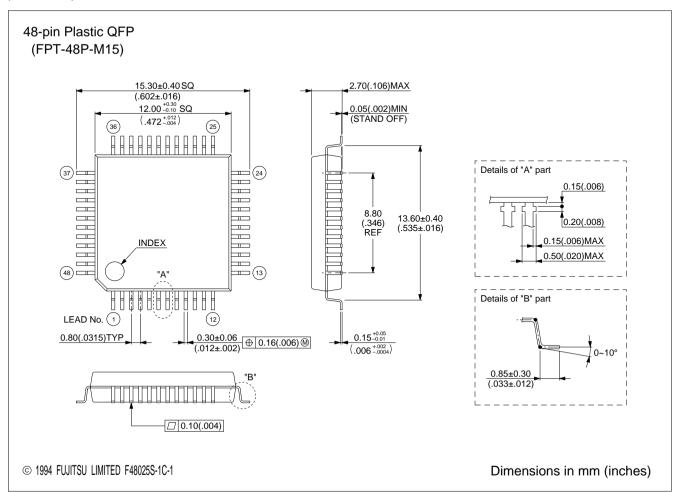
	Part number	MB89	PV910	MB89913	MB89	P915
No.	Fait numper	-101	-102	MB89915	-101	-102
	Specifying procedure	Setting not possible	Setting not possible	Specify when ordering masking	Setting not possible	Setting not possible
1	Selection either single or dual clock Single-clock mode Dual-clock mode	Single clock	Dual clock	Selectable	Single clock	Dual clock
2	Pull-down resistors P17 to P10 P27 to P20 P51, P50	All pins fixed pull-down res		Can be selected per pin.	All pins fixed pull-down res	
3	Voltage to be detected for low- voltage detection reset $3.3 \pm 0.3 \text{ V}$ $3.6 \pm 0.3 \text{ V}$ $4.0 \pm 0.3 \text{ V}$	Cannot be us	ed.	Selectable	Can be set b	y register.

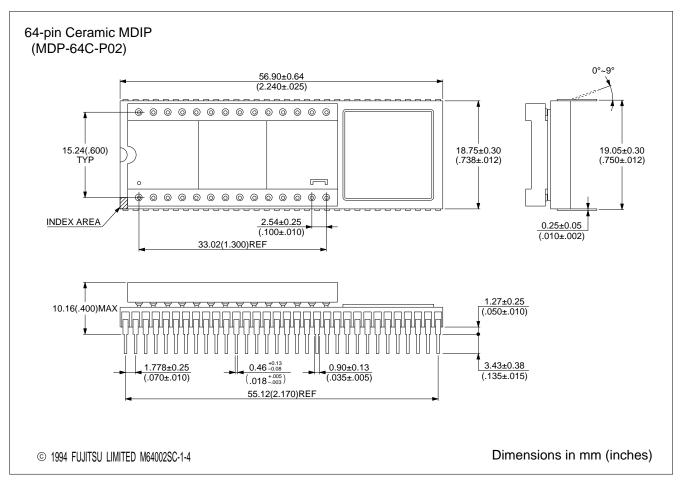
■ ORDERING INFORMATION

Part number	Package	Remarks
MB89913P-SH MB89915P-SH MB89P915P-101-SH MB89P915P-102-SH	48-pin Plastic SH-DIP (DIP-48P-M01)	
MB89913PF MB89915PF MB89P915PF-101 MB89P915PF-102	48-pin Plastic QFP (FPT-48P-M15)	
MB89PV910C-101-ES-SH MB89PV910C-102-ES-SH	64-pin Ceramic MDIP (MDP-64C-P02)	

PACKAGE DIMENSIONS







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